

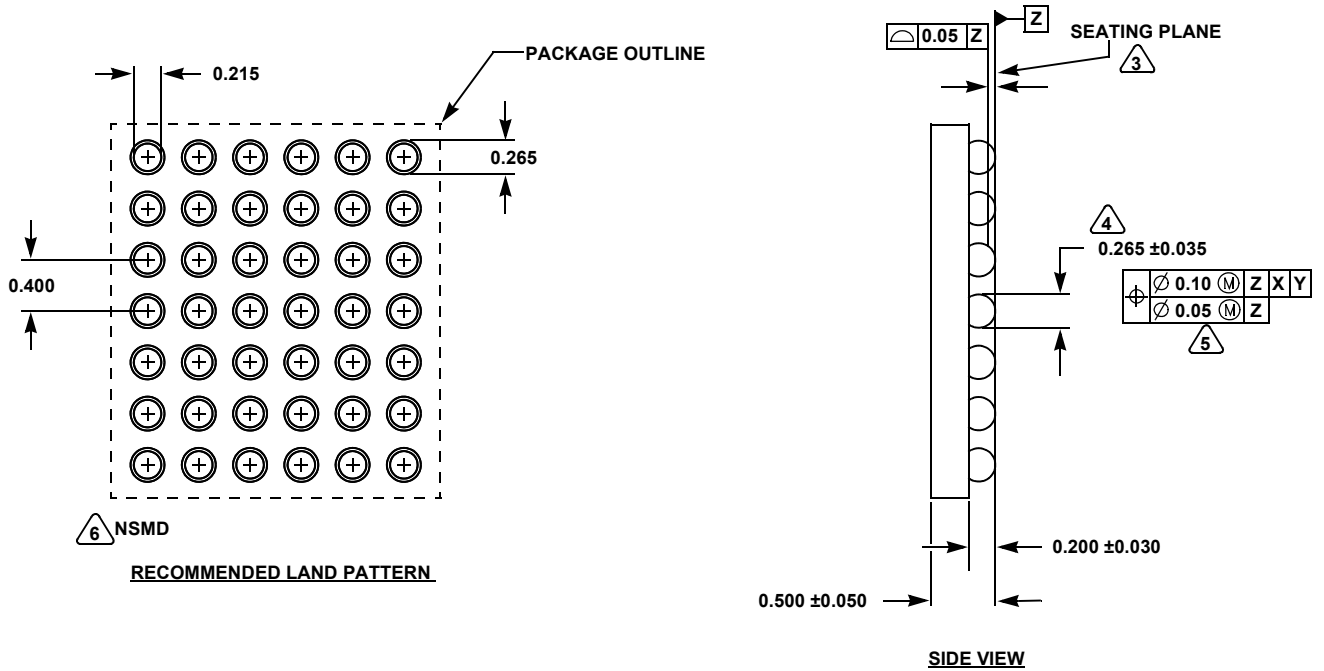
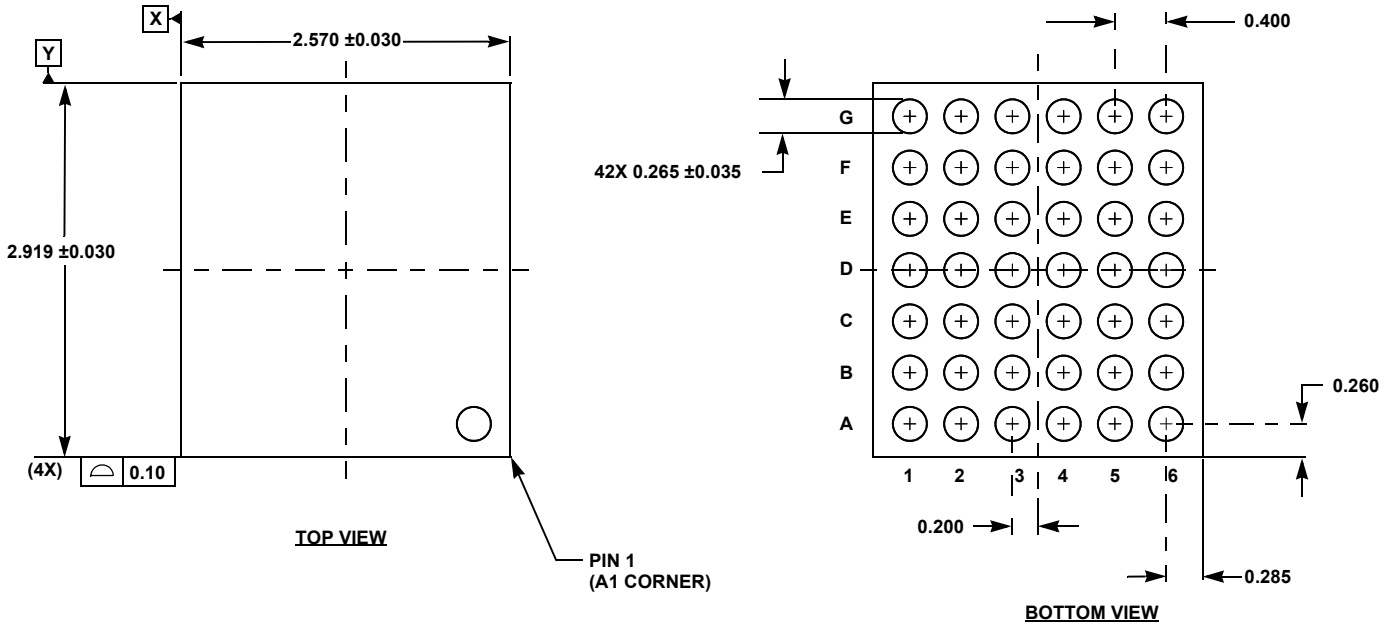
Plastic Packages for Integrated Circuits

Package Outline Drawing

W6x7.42B

42 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)

Rev 0, 1/17



NOTES:

1. All dimensions are in millimeters.

2. Dimensions and tolerance per ASME Y14.5M-1994.

③ Primary datum Z and seating plane are defined by the spherical crowns of the bump.

④ Dimension is measured at the maximum bump diameter parallel to primary datum Z .

⑤ Bump position designation per JESD 95-1, SPP-010.

⑥ NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).